

PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	MDG/21/12541	
1.3 Title of PCI	ST MUAR (Malaysia) LQFP14x14 package leadframe enhancement for listed products	
1.4 Product Category	STM32F07 128K STM32F091x 256K STM32F100 128K STM32F100 512K STM32F103 128K STM32F103 1Mb STM32F103 512K STM32F107 256K STM32F209 1Mb STM32F303 256K STM32F303 512K STM32F412x 1Mb STM32F43x 2Mb STM32F446x 512K STM32F46X 1MB STM32L073x 192K STM32L152V 128K STM32L162 512K STM32L16x 256K STM32L4x 1Mb	
1.5 Issue date	2021-03-01	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	KRISZTINA NEMETH
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Lead frame base material	ST MUAR (Malaysia)

4. Description of change

	Old	New
4.1 Description	Leadframe without Lead Lock Tape	Leadframe with Lead Lock Tape (LLT)
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact	

5. Reason / motivation for change

5.1 Motivation	New state of the art technic
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	tracability ensure by ST internal tool
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7. Timing / schedule

7.1 Date of qualification results	2021-02-10
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7.2 Intended start of delivery	2021-03-25
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
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8.1 Description	12541 MDG-MCD-RER2022 V1.0- PCN12541- ST Muar (Malaysia) LQFP14x14 package leadframe enhancement.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2021-03-01

9. Attachments (additional documentations)			
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12541 Public product.pdf
12541 MDG-MCD-RER2022 V1.0- PCN12541- ST Muar (Malaysia) LQFP14x14 package leadframe enhancement.pdf
12541 PCN12541_Additional information.pdf

10. Affected parts		
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10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F101VCT6	
	STM32F205VGT6	
	STM32F303VET6	
	STM32F205VET7	
	STM32F303VCT6	

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